



#### P-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on) max</sub>	<b>l</b> <sub>D</sub> Τ <sub>C</sub> = +25°C
-40V	$11m\Omega$ @ $V_{GS} = -10V$	-35A
- <del>4</del> 0V	15mΩ @ V <sub>GS</sub> = -4.5V	-30A

## **Description**

This new generation MOSFET has been designed to minimize the onstate resistance ( $R_{DS(ON)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

#### **Applications**

- DC-DC Converters
- Power management functions
- Backlighting

### **Features and Benefits**

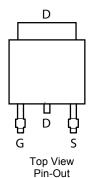
- 100% Unclamped Inductive Switch (UIS) test in production
- Low on-resistance
- Fast switching speed
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Finish annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208<sup>3</sup>
- Weight: 0.33 grams (approximate)







**Equivalent Circuit** 

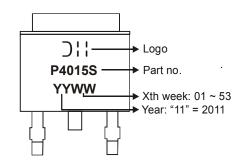
#### Ordering Information (Note 4)

Part Number Compliance		Case	Packaging	
DMP4015SK3-13	Standard	TO252	2,500/Tape & Reel	
DMP4015SK3Q-13	Automotive	TO252	2,500/Tape & Reel	

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html

# **Marking Information**





# Maximum Ratings (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	$V_{DSS}$	-40	V		
Gate-Source Voltage	$V_{GSS}$	±25	V		
Continuous Drain Current (Note 5) V <sub>GS</sub> = -10V	I <sub>D</sub>	-35 -27	Α		
Continuous Drain Current (Note EVV - 40V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-14 -11	Α
Continuous Drain Current (Note 5) V <sub>GS</sub> = -10V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-22 -18	Α
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	-100	Α		
Maximum Body Diode Forward Current (Note 5)	Is	-5.5	Α		
Avalanche Current (Note 6)	I <sub>AS</sub>	-57	Α		
Avalanche Energy (Note 6)	Eas	162	mJ		

# Thermal Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	r -	3.5	- W
Total Power Dissipation (Note 5)	$T_A = +70^{\circ}C$	P <sub>D</sub>	2.2	
Thermal Desigtance, Junction to Ambient (Note 5)	Steady state	_	36	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	15	
Thermal Resistance, Junction to Case (Note 5)  Steady state		$R_{ heta JC}$	4.5	
Operating and Storage Temperature Range		$T_{J,}T_{STG}$	-55 to +150	°C

# Electrical Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)						rest condition	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-40	_	_	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-1	μA	$V_{DS} = -40V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 25V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	-1.5	-2.0	-2.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain Source On Decistance		_	7	11	0	$V_{GS} = -10V, I_D = -9.8A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	9	15	mΩ	$V_{GS} = -4.5V, I_D = -9.8A$	
Forward Transfer Admittance	Y <sub>fs</sub>	_	26	_	S	$V_{DS} = -20V, I_{D} = -9.8A$	
Diode Forward Voltage	V <sub>SD</sub>	_	-0.7	-1.0	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C <sub>iss</sub>	_	4234	_		V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V f = 1.0MHz	
Output Capacitance	Coss	_	1036	_	pF		
Reverse Transfer Capacitance	Crss	_	526	_			
Gate Resistance	R <sub>G</sub>	_	7.77	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge	Qg	_	47.5	_			
Gate-Source Charge	Qgs	_	14.2	_	nC	$V_{DS} = -20V, V_{GS} = -5V$	
Gate-Drain Charge	$Q_{gd}$	_	13.5	_		$I_D = -9.8A$	
Turn-On Delay Time	t <sub>D(on)</sub>	_	13.2	_			
Turn-On Rise Time	t <sub>r</sub>	_	10.0	_		$V_{GS} = -10V, V_{DD} = -20V,$	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	302.7	_	ns	$R_G = 6\Omega$ , $I_D = -1A$	
Turn-Off Fall Time	t <sub>f</sub>	_	137.9	_			

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
- 6. UIS in production with L = 0.1 mH,  $T_J = +25^{\circ}\text{C}$ .
- 7 .Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.



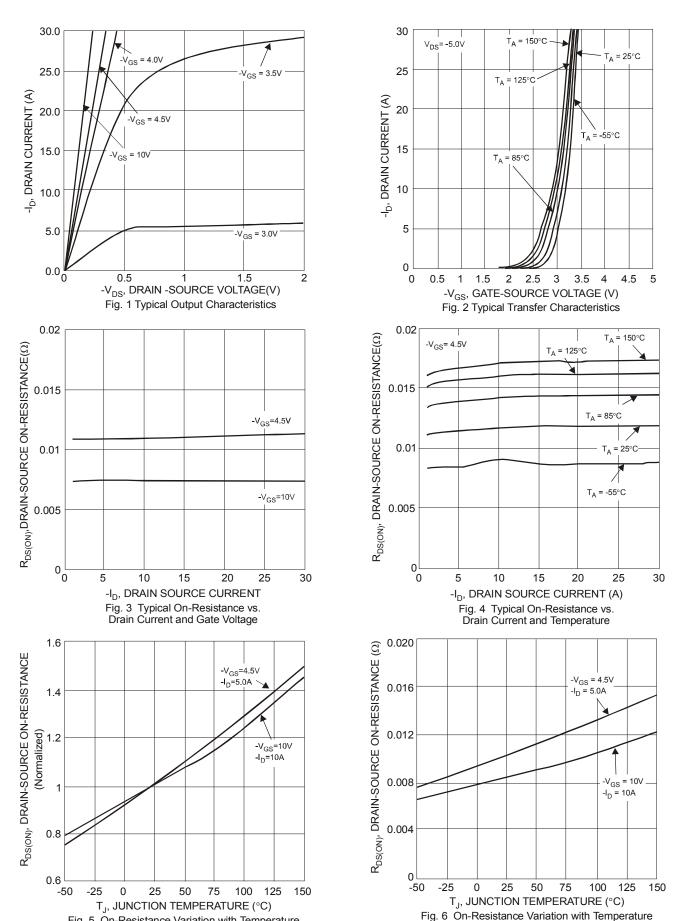


Fig. 5 On-Resistance Variation with Temperature



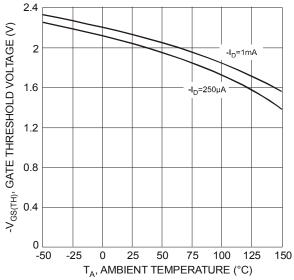
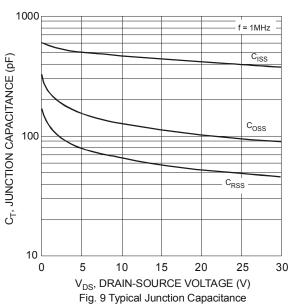
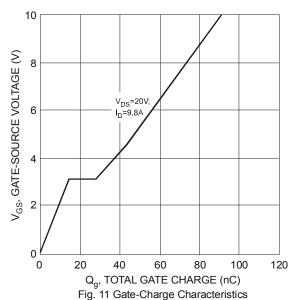
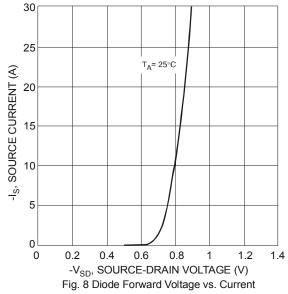


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







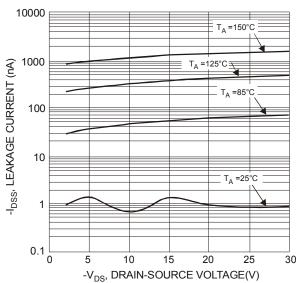


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage

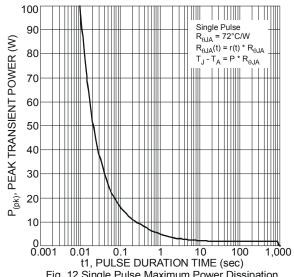
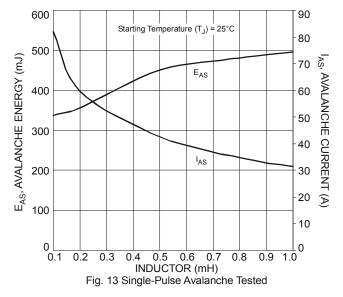
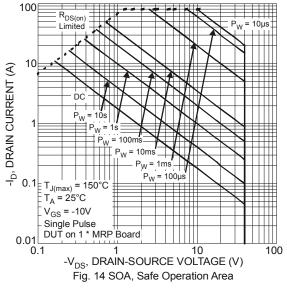
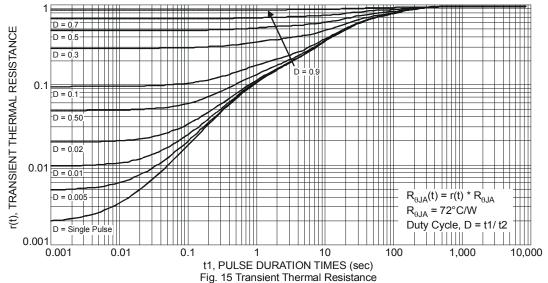


Fig. 12 Single Pulse Maximum Power Dissipation



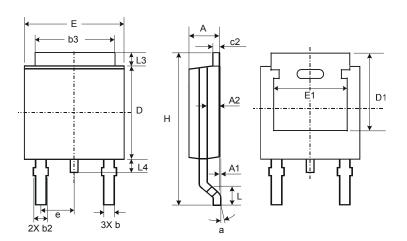






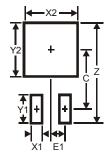


# **Package Outline Dimensions**



TO252					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
c2	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	_	_		
е	_	_	2.286		
Е	6.45	6.70	6.58		
E1	4.32	_	_		
Н	9.40	10.41	9.91		
L	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	<b>L4</b> 0.64		0.83		
а	0°	10°			
All Dimensions in mm					

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	11.6
X1	1.5
X2	7.0
Y1	2.5
Y2	7.0
С	6.9
E1	23



#### **IMPORTANT NOTICE**

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

#### **LIFE SUPPORT**

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2013, Diodes Incorporated

www.diodes.com